



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): NAGAI, et al.

Serial No.: 09/493,210 ✓

Filed: January 28, 2000

For: CIRCUIT TAPE HAVING ADHESIVE FILM, SEMICONDUCTOR  
DEVICE, AND A METHOD FOR MANUFACTURING THE  
SAME

Group: 2827

Examiner: L. Cruz

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503.35443VX1  
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J. BELL  
7/10/02  
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SUPPLEMENTAL AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

July 5, 2002

Sir:

In response to the Communication mailed June 4, 2002, and supplementing  
the Amendment filed April 15, 2002, please further amend the above-identified  
application as follows:

IN THE SPECIFICATION

Please delete the paragraph added to page <sup>8</sup><sub>1</sub> after line 1, in the Amendment  
filed April 15, 2002, and add the following new paragraph on page 8, after line 1, as  
follows:

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--Fig. 9 shows a semiconductor device with a three layer structure for the  
adhesive layer. Shown is core layer (e.g., porous supporting layer) 10 with adhesive